LTCC 材料を用いた積層型方向性結合器の高周波特性解析

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The RF Characteristics Analysis of Vertically Coupled Directional Coupler Comprised of LTCC

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Abstract

The RF characteristics of multi-layered chip directional coupler comprised of LTCCs were successfully calculated on the basis of equivalent circuit. The main and sub electrode lines were coupled with the magnetic coupling coefficient of 0.2 or less. A LTCC consisting of non-magnetic and low-dielectric material was adequate for the directional coupler.

Key Words: Directional Coupler, Directivity, High Frequency, LTCC, Equivalent Circuit Analysis